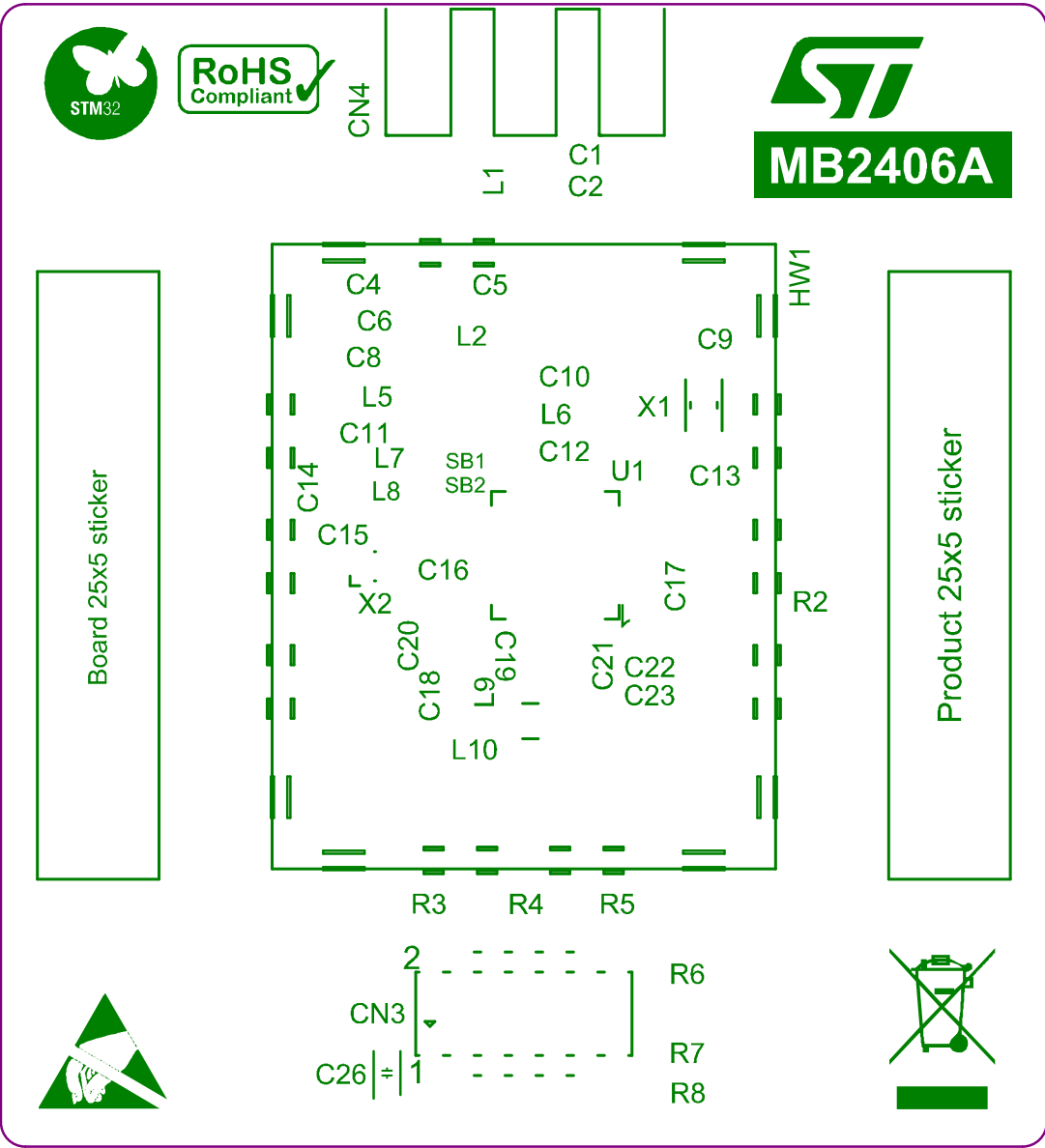
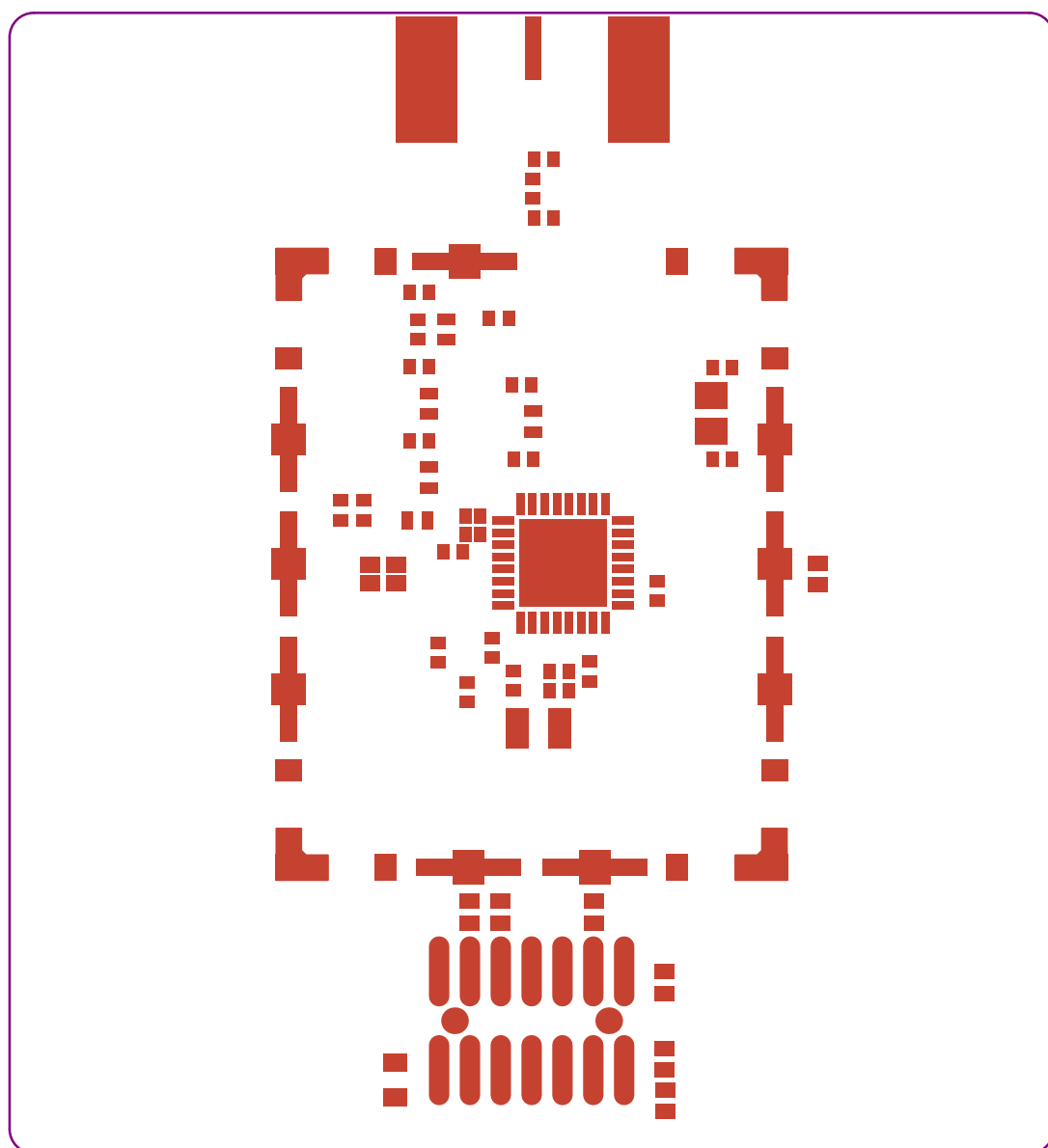
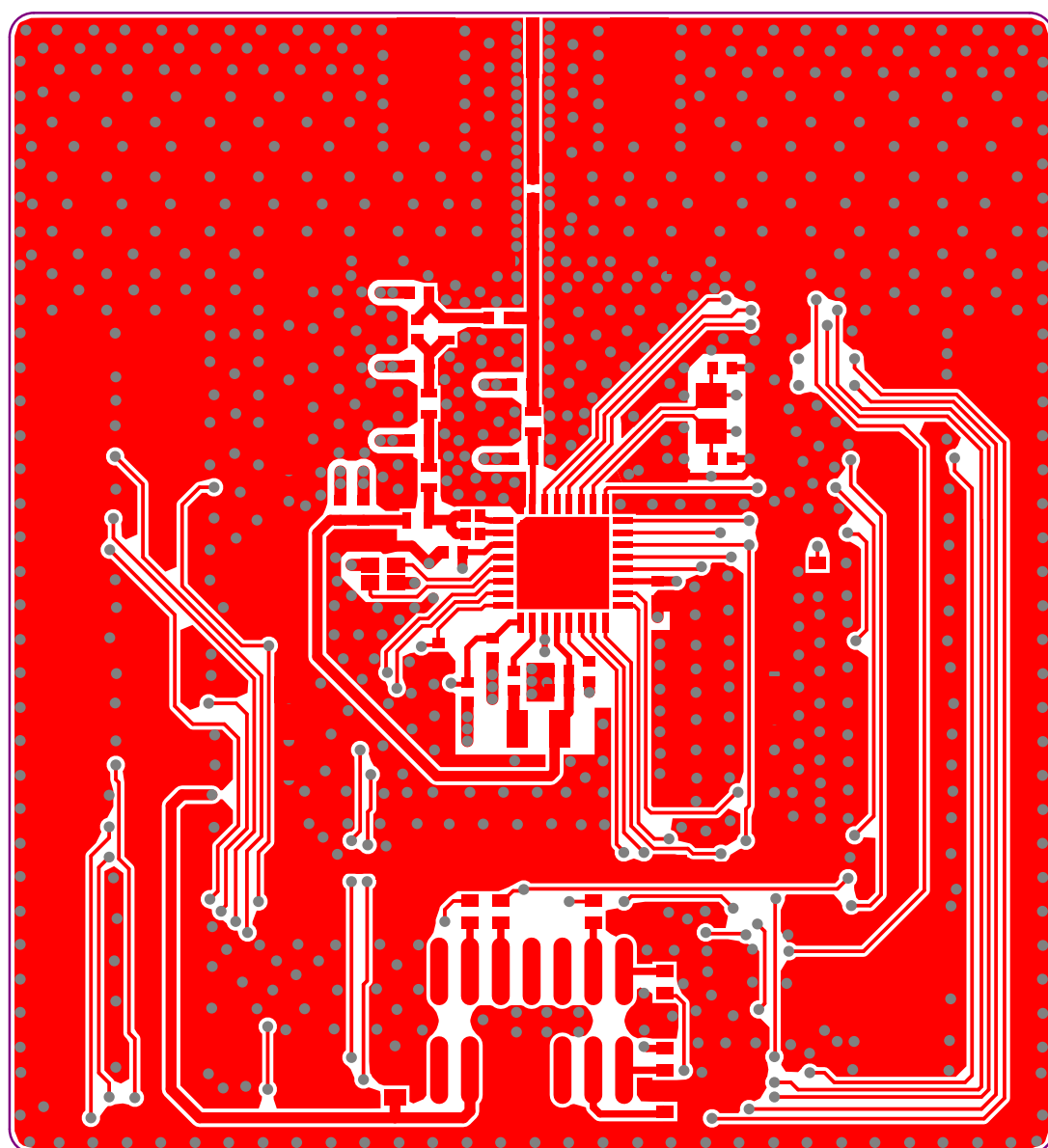




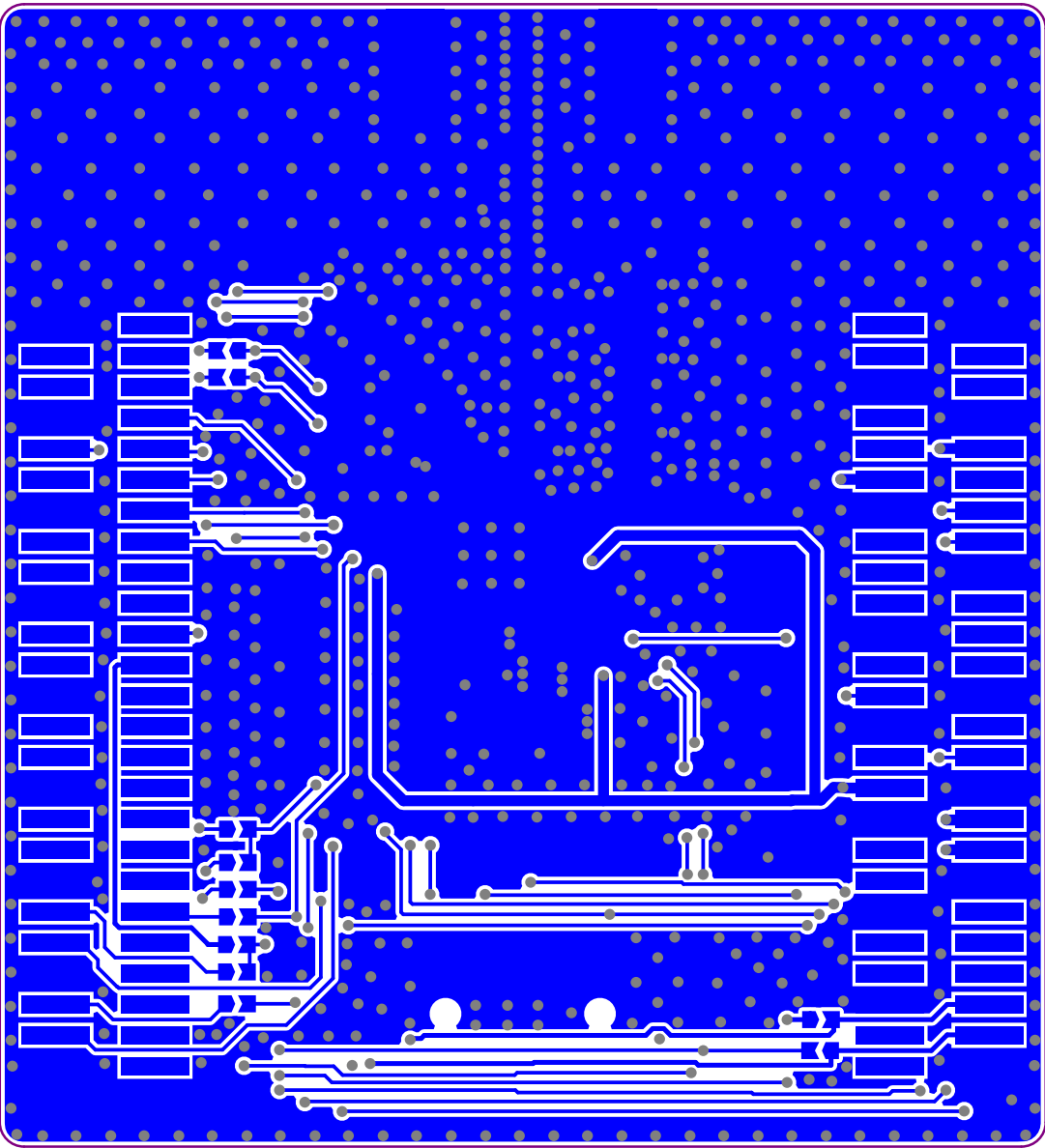
Project: Reference Design STM32WL3R - QFN32 - 2-Layers - SMD		
Layer: Top Overlay	Gerber: .GTO	
Variant: 315MHz_16dBm	Ref: MB2406	
Date: 25/06/2025	Rev: A	



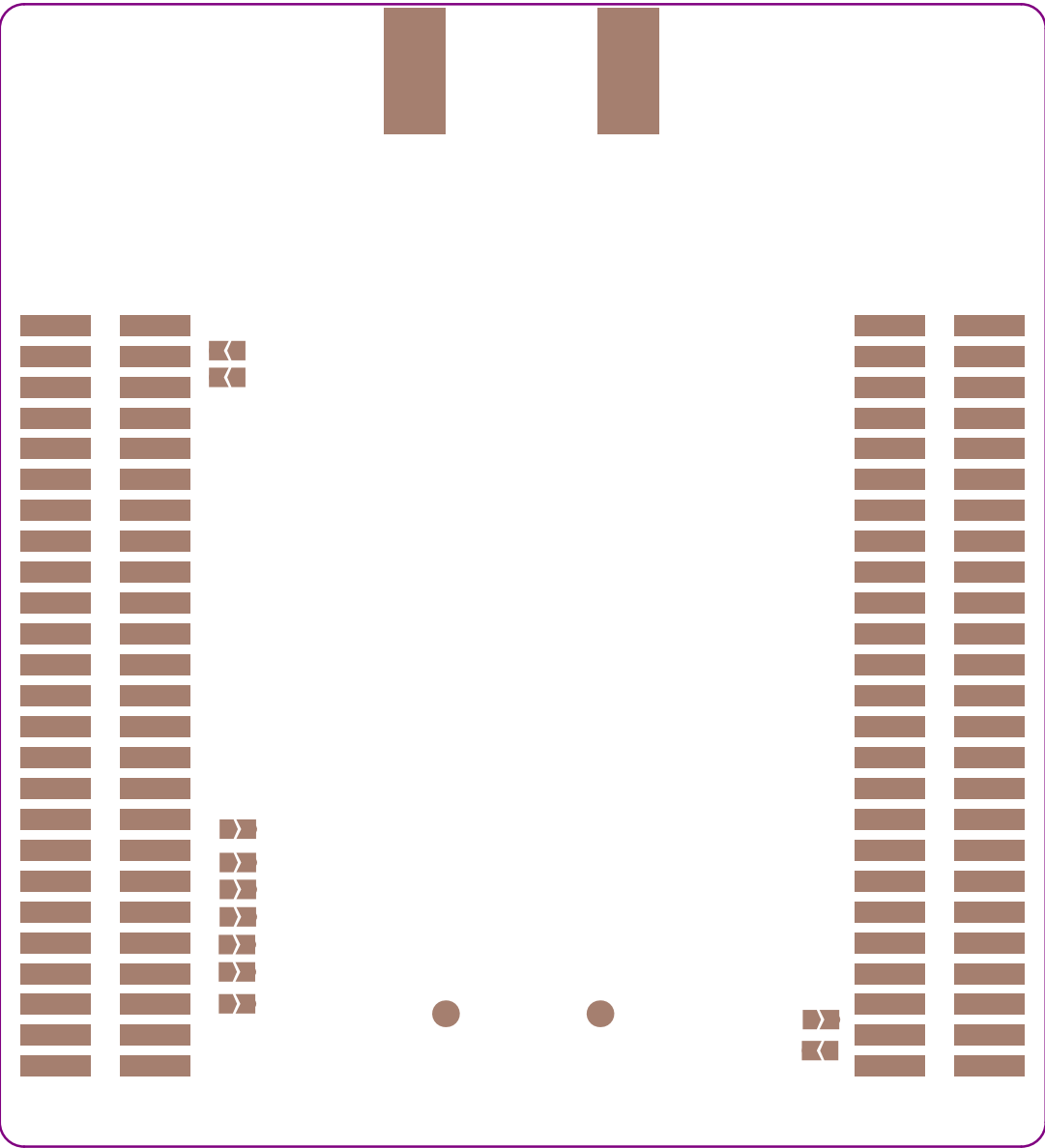
Project: Reference Design STM32WL3R - QFN32 - 2-Layers - SMD		
Layer: Top Solder	Gerber: .GTS	
Variant: 315MHz_16dBm	Ref: MB2406	
Date: 25/06/2025	Rev: A	



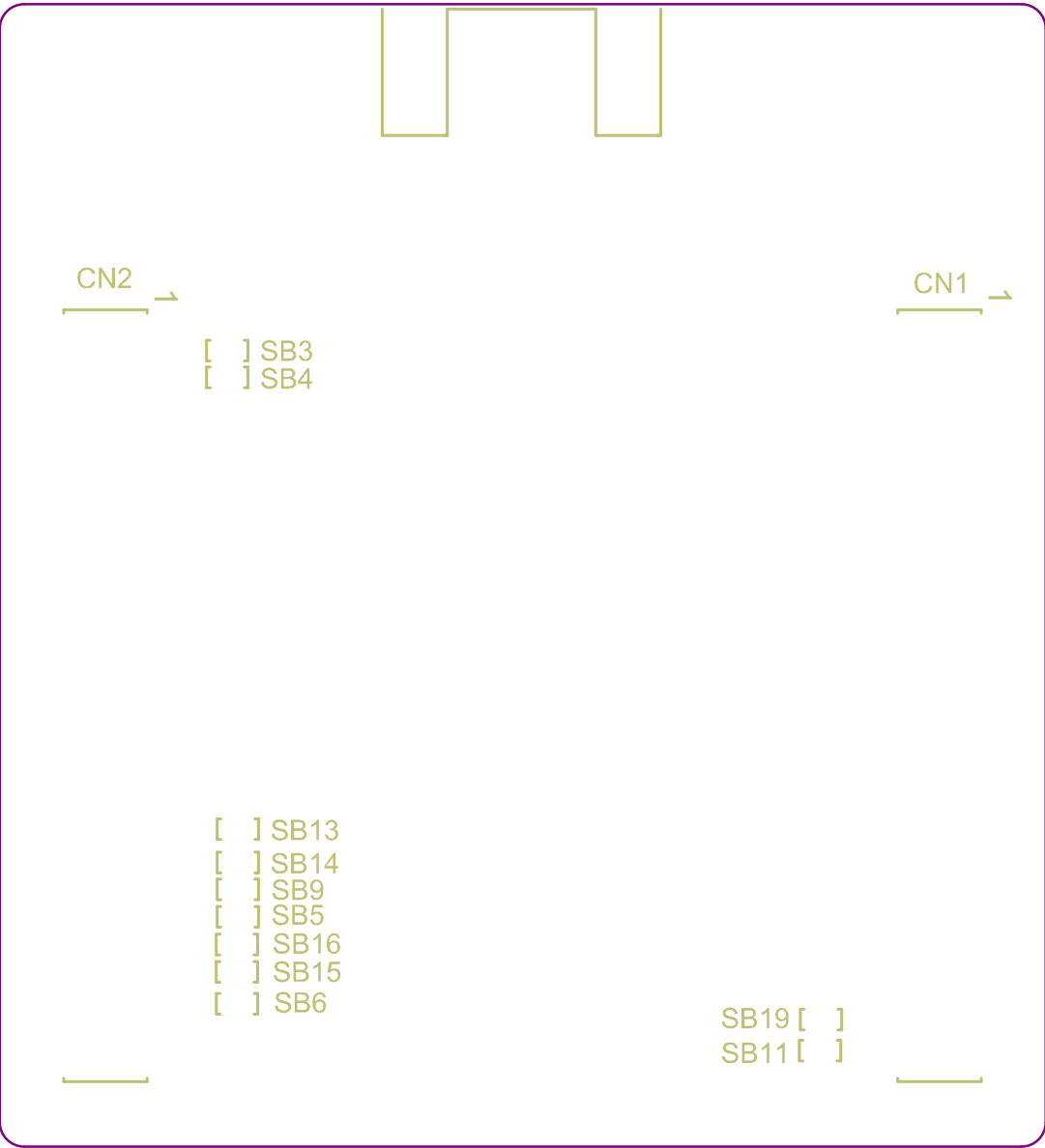
Project: Reference Design STM32WL3R - QFN32 - 2-Layers - SMD		
Layer: Top Layer	Gerber: .GTL	
Variant: 315MHz_16dBm	Ref: MB2406	
Date: 25/06/2025	Rev: A	



Project: Reference Design STM32WL3R - QFN32 - 2-Layers - SMD		
Layer: Bottom Layer	Gerber:.GBL	
Variant: 315MHz_16dBm	Ref: MB2406	
Date: 25/06/2025	Rev: A	



Project: Reference Design STM32WL3R - QFN32 - 2-Layers - SMD		
Layer: Bottom Solder	Gerber:.GBS	
Variant: 315MHz_16dBm	Ref: MB2406	
Date: 25/06/2025	Rev: A	



Project: Reference Design STM32WL3R - QFN32 - 2-Layers - SMD		
Layer: Bottom Overlay	Gerber: .GBO	
Variant: 315MHz_16dBm	Ref: MB2406	
Date: 25/06/2025	Rev: A	

PCB SPECIFICATIONS :

A. MATERIAL :

B. MATERIAL FAMILY :

C. SOLDERMASK COLOR :

D. SILKSCREEN COLOR :

E. SURFACE FINISH :

F. IMPEDANCE CONTROL :

G. THROUGH VIA :

H. STACK-UP :

FR-4

VT-47

☐ GREEN

☒ WHITE

☒ ENIG

☐ HASL

☐ NO

☐ TG-170

☒ BLUE

☐ YELLOW

☐ IMMERSION SILVER

☐ HASL (PB-FREE)

☒ YES

☐ TG-150

☐ RED

☐ BLACK

☐ IMMERSION TIN

☐ GOLDEN FINGER

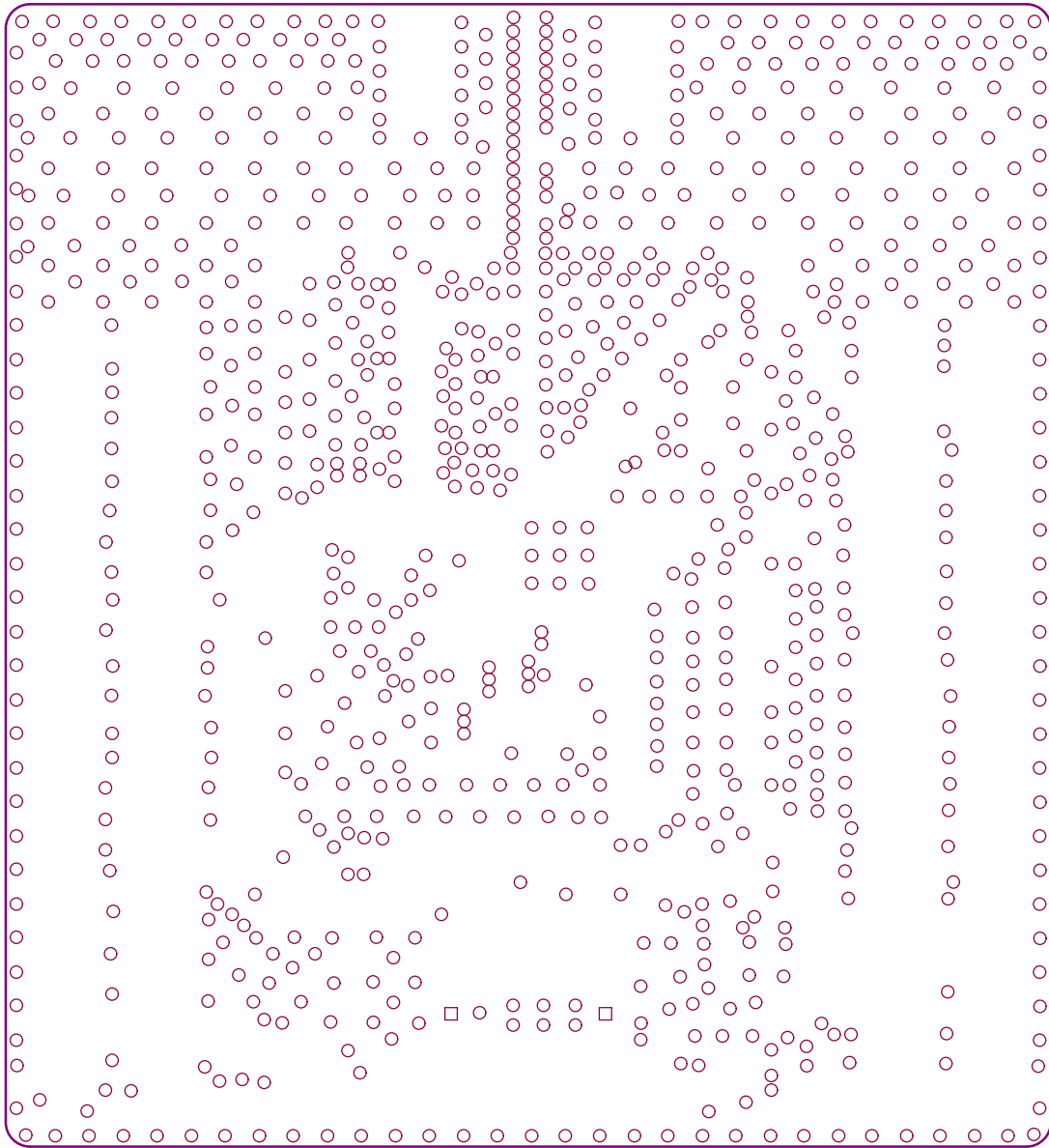
☒ TG-140

☐ BLACK

☐ PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.

PLUG MATERIAL : ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.



Layer	Name	Material	Thickness	Constant
	Top Overlay			
	Top Solder	Solder Resist	0,010mm	3.5
1	Top Layer	Copper	0,041mm	
	Dielectric 2	FR4	0,914mm	4.3
2	Bottom Layer	Copper	0,041mm	
	Bottom Solder	Solder Resist	0,010mm	3.5
	Bottom Overlay			

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Hole Length
○	906	0.20mm (7.87mil)	PTH	Round	Top Layer - Bottom Layer	Via	-
□	2	1.00mm (39.37mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-
	908 Total						

PCB : TYPE 3

ASPECT-RATIO, AXE Z :
6 :1 à 8 :1
LEVEL "B"

MINIMUN PARAMETERS

DEFAULT
TRACKS : 0.150mm
GAPS : 0.150mm

Project: Reference Design STM32WL3R - QFN32 - 2-Layers - SMD		
Layer: Drill Drawing	Gerber: .DRL	
Variant: 315MHz_16dBm	Ref: MB2406	
Date: 25/06/2025	Rev: A	